Title (en)

VERTICALLY STACKABLE SOCKETS FOR CHIP MODULES

Title (de)

VERTIKAL STAPELBARE FASSUNGSANORDNUNG FÜR INTEGRIERTE SCHALTUNGS-MODULE

Title (fr)

SUPPORTS POUVANT ÊTRE EMPILÉS VERTICALEMENT POUR DES MODULES DE PUCES

Publication

EP 2457291 B1 20160323 (EN)

Application

EP 10701050 A 20100107

Priority

- US 50580809 A 20090720
- US 2010020307 W 20100107

Abstract (en)

[origin: US2011014802A1] The socket system comprises a set of vertically-stackable sockets. A first socket mounts on a printed circuit board to receive a first chip module, and a second socket stacks on the first socket to receive a second chip module. The first socket includes a first set of embedded contacts to electrically connect the first chip module to the printed circuit board, and a second set of embedded contacts to electrically connect the second socket to the printed circuit board. The second socket includes a third set of embedded contacts to electrically connect the second chip module to the printed circuit board. System upgrades are enabled by replacing the chip modules.

IPC 8 full level

H01L 23/32 (2006.01); **H01L 23/552** (2006.01); **H01L 25/10** (2006.01); **H05K 7/02** (2006.01); **H05K 7/10** (2006.01)

CPC (source: EP US)

H01L 23/32 (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 25/105** (2013.01 - EP US); **H05K 7/023** (2013.01 - EP US); **H05K 7/1023** (2013.01 - EP US); H01L 2225/107 (2013.01 - EP US); H01L 2225/1082 (2013.01 - EP US); H01L 2924/0002 (2013.01 - EP US); H01L 2924/09701 (2013.01 - EP US); H01L 2924/14 (2013.01 - EP US); H01L 2924/3025 (2013.01 - EP US)

C-Set (source: EP US)

H01L 2924/0002 + H01L 2924/00

Citation (examination)

- US 4437718 A 19840320 - SELINKO GEORGE J [US]
- US 3593064 A 19710713 - WAGNER HORST, et al
- WO 0251224 A2 20020627 - SYNERGESTIC COMPUTING SYSTEMS [DK], et al

Designated contracting state (EPC)

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DOCDB simple family (publication)

US 2011014802 A1 20110120; **US 7922523 B2 20110412**; CN 102474036 A 20120523; CN 102474036 B 20140430; EP 2457291 A1 20120530; EP 2457291 B1 20160323; WO 2011011096 A1 20110127

DOCDB simple family (application)

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